



**ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOIC 8-LEAD (EY)**

<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
HAST	602	87,920	130 °C, 85 % RH	0	0.00
Power Cycle	737	11,582,096	DELTA Tj = 100	0	0.00
Pressure Pot	1,048	128,328	121°, 15 PSIG	0	0.00
Solder DUNK	135	405	260 °C, 10 SEC	0	0.00
Solderability	120	960	883 M2003	0	0.00
Temp Cycle	1,048	642,730	-65 °C – 150 °C	0	0.00